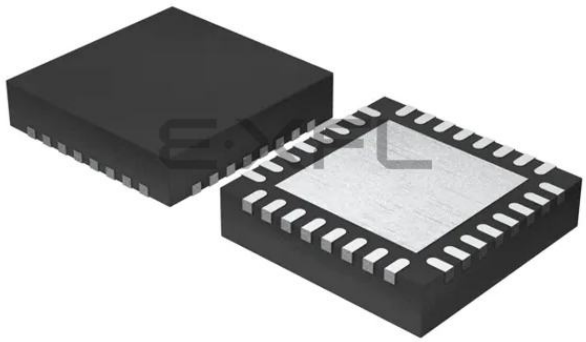

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	24
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.85V ~ 3.8V
Data Converters	A/D 24x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TJ)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32pg1b100f256im32-c0

2. Ordering Information

Ordering Code	Flash (kB)	RAM (kB)	DC-DC Converter	GPIO	Package	Temp Range
EFM32PG1B200F256GM48-C0	256	32	Yes	32	QFN48	-40 to +85
EFM32PG1B200F256IM48-C0	256	32	Yes	32	QFN48	-40 to +125
EFM32PG1B200F128GM48-C0	128	32	Yes	32	QFN48	-40 to +85
EFM32PG1B200F256GM32-C0	256	32	Yes	20	QFN32	-40 to +85
EFM32PG1B200F256IM32-C0	256	32	Yes	20	QFN32	-40 to +125
EFM32PG1B200F128GM32-C0	128	32	Yes	20	QFN32	-40 to +85
EFM32PG1B100F256GM32-C0	256	32	No	24	QFN32	-40 to +85
EFM32PG1B100F256IM32-C0	256	32	No	24	QFN32	-40 to +125
EFM32PG1B100F128GM32-C0	128	32	No	24	QFN32	-40 to +85

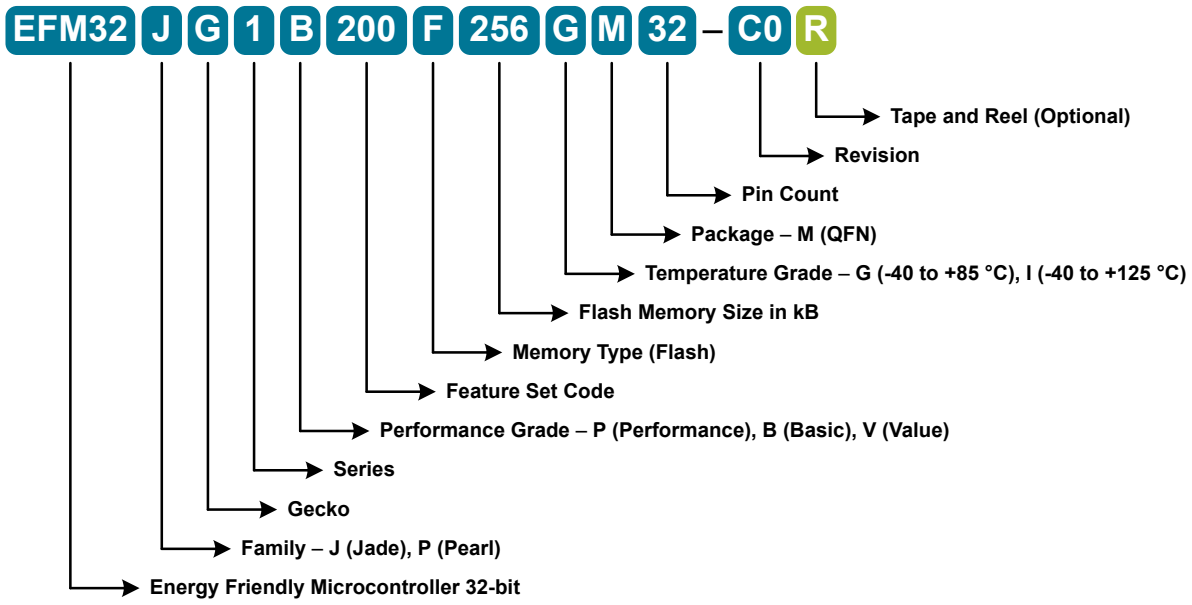


Figure 2.1. OPN Decoder

3.11 Memory Map

The EFM32PG1 memory map is shown in the figures below. RAM and flash sizes are for the largest memory configuration.

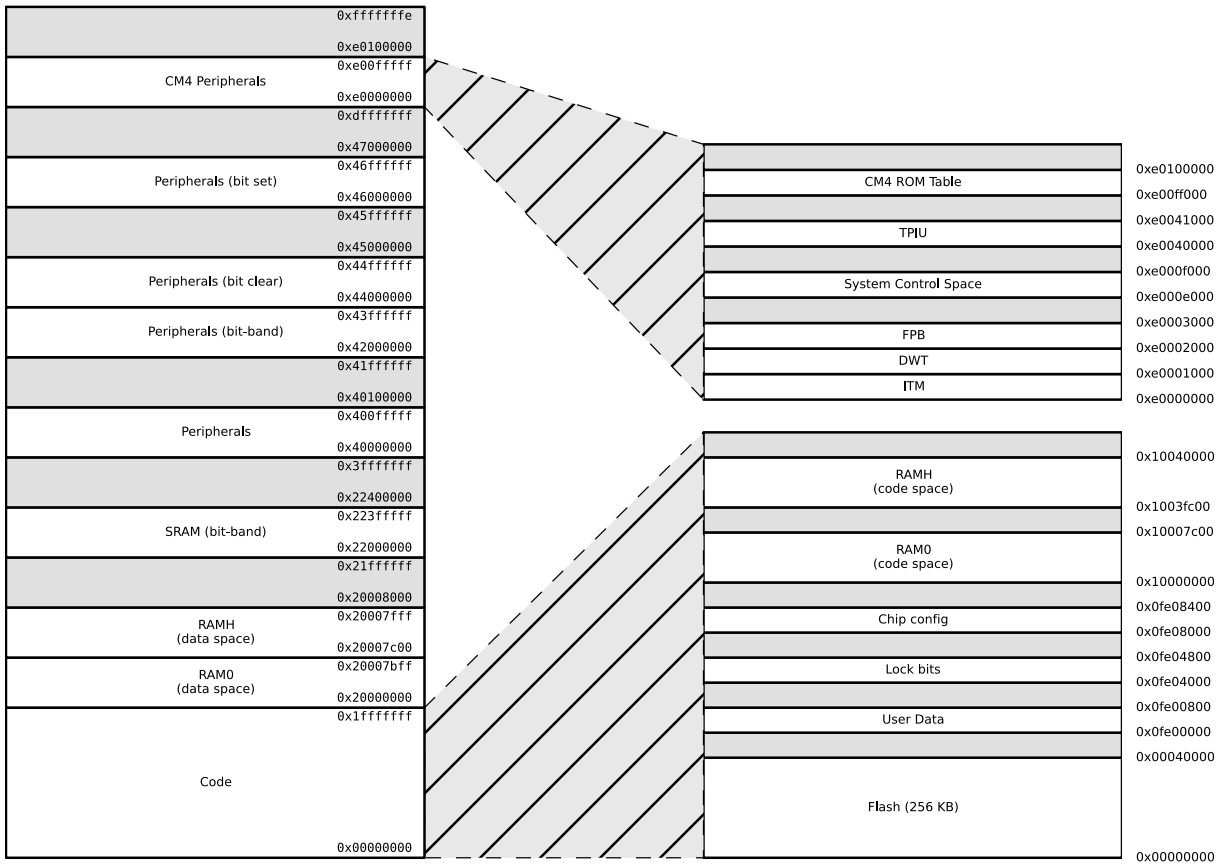


Figure 3.2. EFM32PG1 Memory Map — Core Peripherals and Code Space

4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the following conditions, unless stated otherwise:

- Typical values are based on T_{AMB}=25 °C and V_{DD}= 3.3 V, by production test and/or technology characterization.
- Minimum and maximum values represent the worst conditions across supply voltage, process variation, and operating temperature, unless stated otherwise.

Refer to Table 4.2 General Operating Conditions on page 11 for more details about operational supply and temperature limits.

4.1.1 Absolute Maximum Ratings

Stresses above those listed below may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. For more information on the available quality and reliability data, see the Quality and Reliability Monitor Report at http://www.silabs.com/support/quality/pages/default.aspx.

Table 4.1. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Storage temperature range	T_{STG}		-50	—	150	°C
External main supply voltage	V_{DDMAX}		0	—	3.8	V
External main supply voltage ramp rate	$V_{DDRAMPMAX}$		—	—	1	V / µs
Voltage on any 5V tolerant GPIO pin[1]	V_{DIGPIN}		-0.3	—	Min of 5.25 and IOVDD +2	V
Voltage on non-5V tolerant GPIO pins			-0.3	—	IOVDD+0.3	V
Voltage on HFXO pins	$V_{HFXOPIN}$		-0.3	—	1.4	V
Total current into VDD power lines (source)	I_{VDDMAX}		—	—	200	mA
Total current into VSS ground lines (sink)	I_{VSSMAX}		—	—	200	mA
Current per I/O pin (sink)	I_{IOMAX}		—	—	50	mA
Current per I/O pin (source)			—	—	50	mA
Current for all I/O pins (sink)	$I_{IOALLMAX}$		—	—	200	mA
Current for all I/O pins (source)			—	—	200	mA
Voltage difference between AVDD and VREGVDD	ΔV_{DD}		—	—	0.3	V
Junction Temperature for -G grade devices	T_J		-40	—	105	°C
Junction Temperature for -I grade devices			-40	—	125	°C

Note:

1. When a GPIO pin is routed to the analog module through the APORT, the maximum voltage = IOVDD.

4.1.9 Flash Memory Characteristics

Table 4.15. Flash Memory Characteristics[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC_{FLASH}		10000	—	—	cycles
Flash data retention	RET_{FLASH}	T_{AMB} ≤ 85 °C	10	—	—	years
		T_{AMB} ≤ 125 °C	10	—	—	years
Word (32-bit) programming time	t_{W_PROG}		20	26	40	µs
Page erase time	t_{PERASE}		20	27	40	ms
Mass erase time	t_{MERASE}		20	27	40	ms
Device erase time[2]	t_{DERASE}	T_{AMB} ≤ 85 °C	—	60	74	ms
		T_{AMB} ≤ 125 °C	—	60	78	ms
Page erase current[3]	I_{ERASE}		—	—	3	mA
Mass or Device erase current[3]			—	—	5	mA
Write current[3]	I_{WRITE}		—	—	3	mA

Note:

1. Flash data retention information is published in the Quarterly Quality and Reliability Report.
2. Device erase is issued over the AAP interface and erases all flash, SRAM, the Lock Bit (LB) page, and the User data page Lock Word (ULW)
3. Measured at 25°C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Settling time, (output settled within 1% of steady state value)	t_{IDAC_SETTLE}	Range setting is changed	—	5	—	µs
		Step value is changed	—	1	—	µs
Current consumption in EM0 or EM1 [2]	I_{IDAC}	Source mode, excluding output current	—	8.9	13	µA
		Sink mode, excluding output current	—	12	16	µA
Current consumption in EM2 or EM3[2]		Source mode, excluding output current, duty cycle mode, T = 25 °C	—	1.04	—	µA
		Sink mode, excluding output current, duty cycle mode, T = 25 °C	—	1.08	—	µA
		Source mode, excluding output current, duty cycle mode, T ≥ 85 °C	—	8.9	—	µA
		Sink mode, excluding output current, duty cycle mode, T ≥ 85 °C	—	12	—	µA
Output voltage compliance in source mode, source current change relative to current sourced at 0 V	I_{COMP_SRC}	RANGESEL1=0, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-100 mv)	—	0.04	—	%
		RANGESEL1=1, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-100 mV)	—	0.02	—	%
		RANGESEL1=2, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-150 mV)	—	0.02	—	%
		RANGESEL1=3, output voltage = min(V_{IOVDD}, V_{AVDD}[2]-250 mV)	—	0.02	—	%
Output voltage compliance in sink mode, sink current change relative to current sunk at IOVDD	I_{COMP_SINK}	RANGESEL1=0, output voltage = 100 mV	—	0.18	—	%
		RANGESEL1=1, output voltage = 100 mV	—	0.12	—	%
		RANGESEL1=2, output voltage = 150 mV	—	0.08	—	%
		RANGESEL1=3, output voltage = 250 mV	—	0.02	—	%

Note:

1. In IDAC_CURPROG register
2. The IDAC is supplied by either AVDD, DVDD, or IOVDD based on the setting of ANASW in the EMU_PWRCTRL register and PWRSEL in the IDAC_CTRL register. Setting PWRSEL to 1 selects IOVDD. With PWRSEL cleared to 0, ANASW selects between AVDD (0) and DVDD (1).

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Comparator delay[4]	$t_{ACMPDELAY}$	BIASPROG[2] = 1, FULLBIAS[2] = 0	—	30	—	µs
		BIASPROG[2] = 0x10, FULLBIAS[2] = 0	—	3.7	—	µs
		BIASPROG[2] = 0x20, FULLBIAS[2] = 1	—	35	—	ns
Offset voltage	$V_{ACMPOFFSET}$	BIASPROG[2] =0x10, FULLBIAS[2] = 1	-35	—	35	mV
Reference Voltage	$V_{ACMPREF}$	Internal 1.25 V reference	1	1.25	1.47	V
		Internal 2.5 V reference	2	2.5	2.8	V
Capacitive Sense Internal Resistance	R_{CSRES}	CSRESSEL[5] = 0	—	inf	—	kΩ
		CSRESSEL[5] = 1	—	15	—	kΩ
		CSRESSEL[5] = 2	—	27	—	kΩ
		CSRESSEL[5] = 3	—	39	—	kΩ
		CSRESSEL[5] = 4	—	51	—	kΩ
		CSRESSEL[5] = 5	—	102	—	kΩ
		CSRESSEL[5] = 6	—	164	—	kΩ
		CSRESSEL[5] = 7	—	239	—	kΩ

Note:

1. ACMPVDD is a supply chosen by the setting in ACMPn_CTRL_PWRSEL and may be IOVDD, AVDD or DVDD
2. In ACMPn_CTRL register
3. In ACMPn_HYSTERESIS register
4. ±100 mV differential drive
5. In ACMPn_INPUTSEL register

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given as:

$$I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$$

$I_{ACMPREF}$ is zero if an external voltage reference is used.

I2C Fast-mode (Fm)

Table 4.22. I2C Fast-mode (Fm)[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency[2]	f_{SCL}		0	—	400	kHz
SCL clock low time	t_{LOW}		1.3	—	—	µs
SCL clock high time	t_{HIGH}		0.6	—	—	µs
SDA set-up time	$t_{SU,DAT}$		100	—	—	ns
SDA hold time[3]	$t_{HD,DAT}$		100	—	900	ns
Repeated START condition set-up time	$t_{SU,STA}$		0.6	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$		0.6	—	—	µs
STOP condition set-up time	$t_{SU,STO}$		0.6	—	—	µs
Bus free time between a STOP and START condition	t_{BUF}		1.3	—	—	µs

Note:
1. For CLHR set to 1 in the I2Cn_CTRL register
2. For the minimum HFPERCLK frequency required in Fast-mode, refer to the I2C chapter in the reference manual
3. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW})

I2C Fast-mode Plus (Fm+)

Table 4.23. I2C Fast-mode Plus (Fm+)[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency[2]	f_{SCL}		0	—	1000	kHz
SCL clock low time	t_{LOW}		0.5	—	—	µs
SCL clock high time	t_{HIGH}		0.26	—	—	µs
SDA set-up time	$t_{SU,DAT}$		50	—	—	ns
SDA hold time	$t_{HD,DAT}$		100	—	—	ns
Repeated START condition set-up time	$t_{SU,STA}$		0.26	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$		0.26	—	—	µs
STOP condition set-up time	$t_{SU,STO}$		0.26	—	—	µs
Bus free time between a STOP and START condition	t_{BUF}		0.5	—	—	µs

Note:
1. For CLHR set to 0 or 1 in the I2Cn_CTRL register
2. For the minimum HFPERCLK frequency required in Fast-mode Plus, refer to the I2C chapter in the reference manual

SPI Slave Timing

Table 4.25. SPI Slave Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCKL period [1] [2]	t_{SCLK_sl}		2 * $t_{HFPERCLK}$	—	—	ns
SCLK high period[1] [2]	t_{SCLK_hi}		3 * $t_{HFPERCLK}$	—	—	ns
SCLK low period [1] [2]	t_{SCLK_lo}		3 * $t_{HFPERCLK}$	—	—	ns
CS active to MISO [1] [2]	$t_{CS\_ACT\_MI}$		4	—	50	ns
CS disable to MISO [1] [2]	$t_{CS\_DIS\_MI}$		4	—	50	ns
MOSI setup time [1] [2]	t_{SU_MO}		4	—	—	ns
MOSI hold time [1] [2]	t_{H_MO}		3 + 2 * $t_{HFPERCLK}$	—	—	ns
SCLK to MISO [1] [2]	t_{SCLK_MI}		16 + $t_{HFPERCLK}$	—	66 + 2 * $t_{HFPERCLK}$	ns

Note:
1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)
2. Measurement done with 8 pF output loading at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

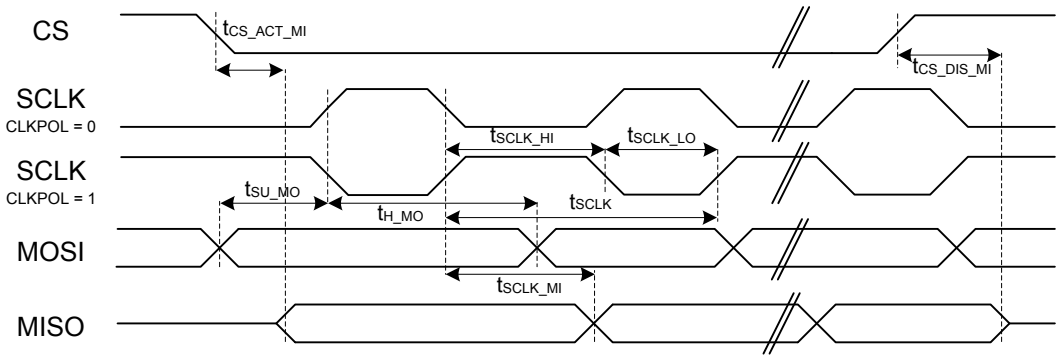


Figure 4.2. SPI Slave Timing Diagram

4.2 Typical Performance Curves

Typical performance curves indicate typical characterized performance under the stated conditions.

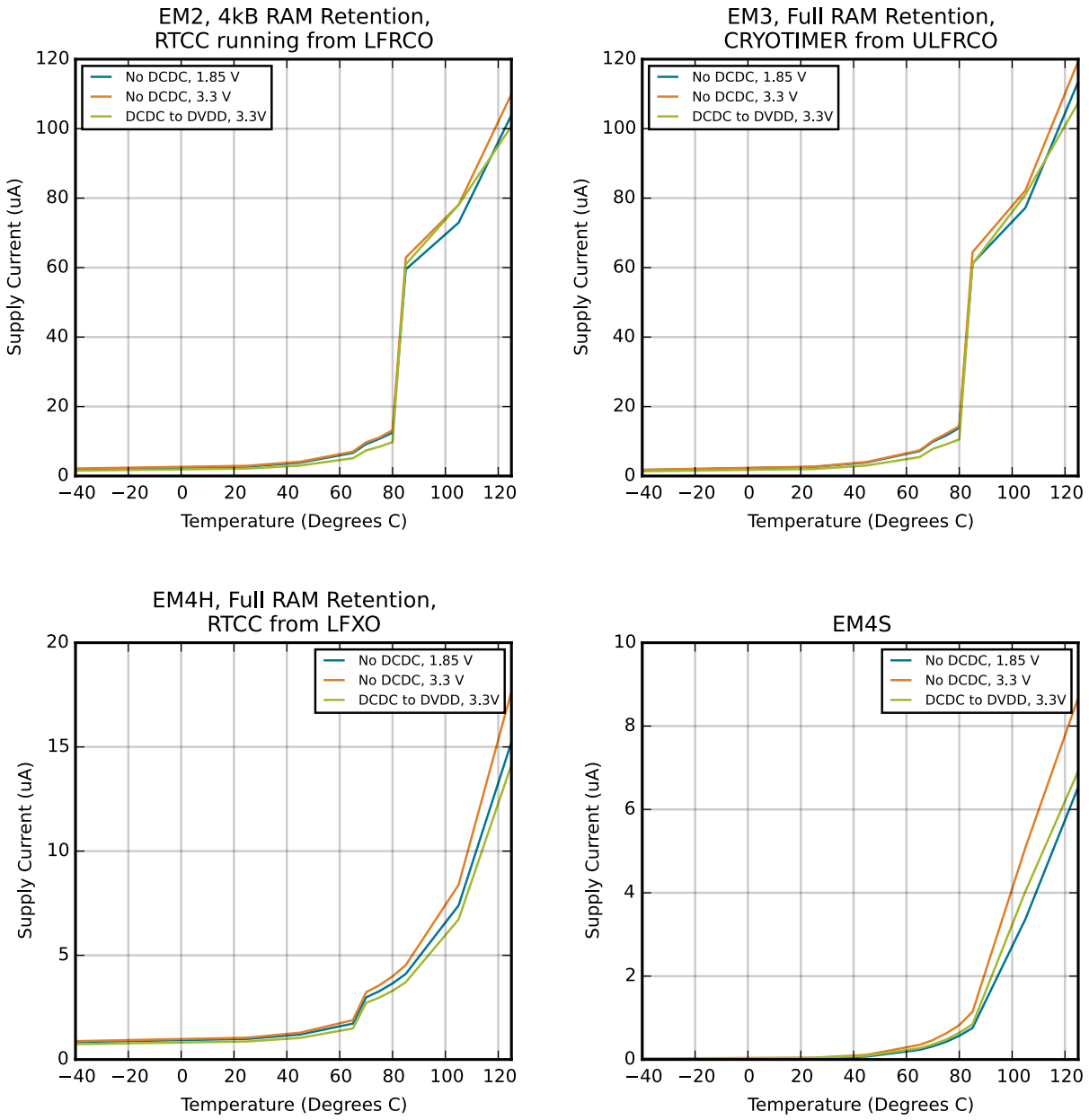


Figure 4.5. EM2, EM3, EM4H and EM4S Typical Supply Current

6. Pin Definitions

6.1 EFM32PG1 QFN48 with DC-DC Definition

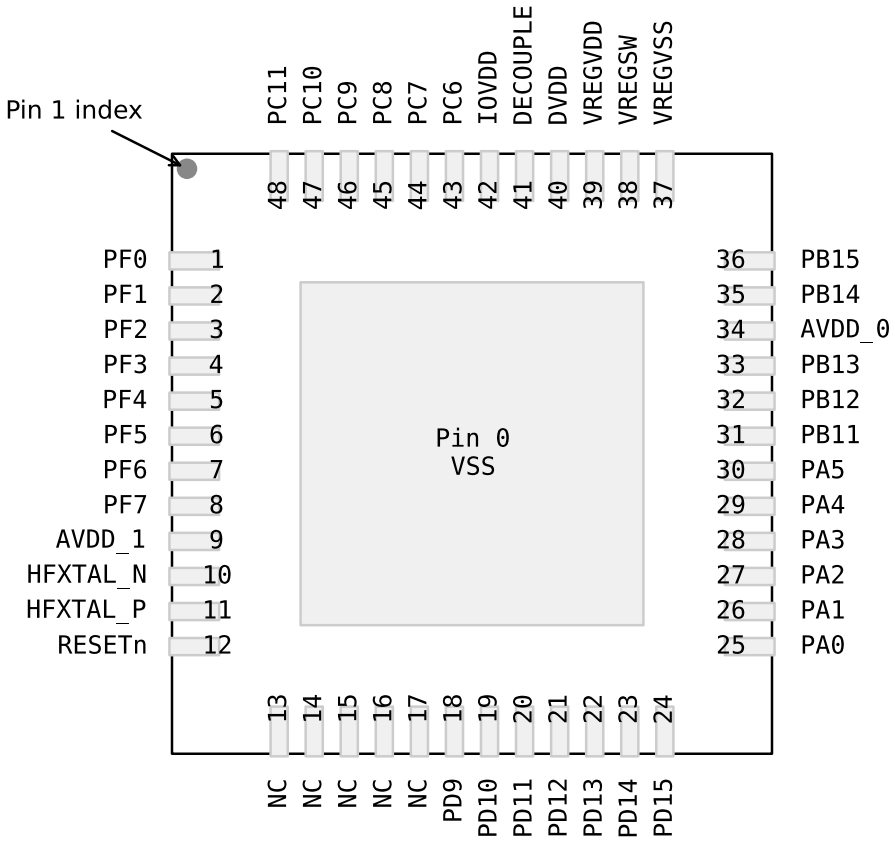


Figure 6.1. EFM32PG1 QFN48 with DC-DC Pinout

6.2 EFM32PG1 QFN32 without DC-DC Definition

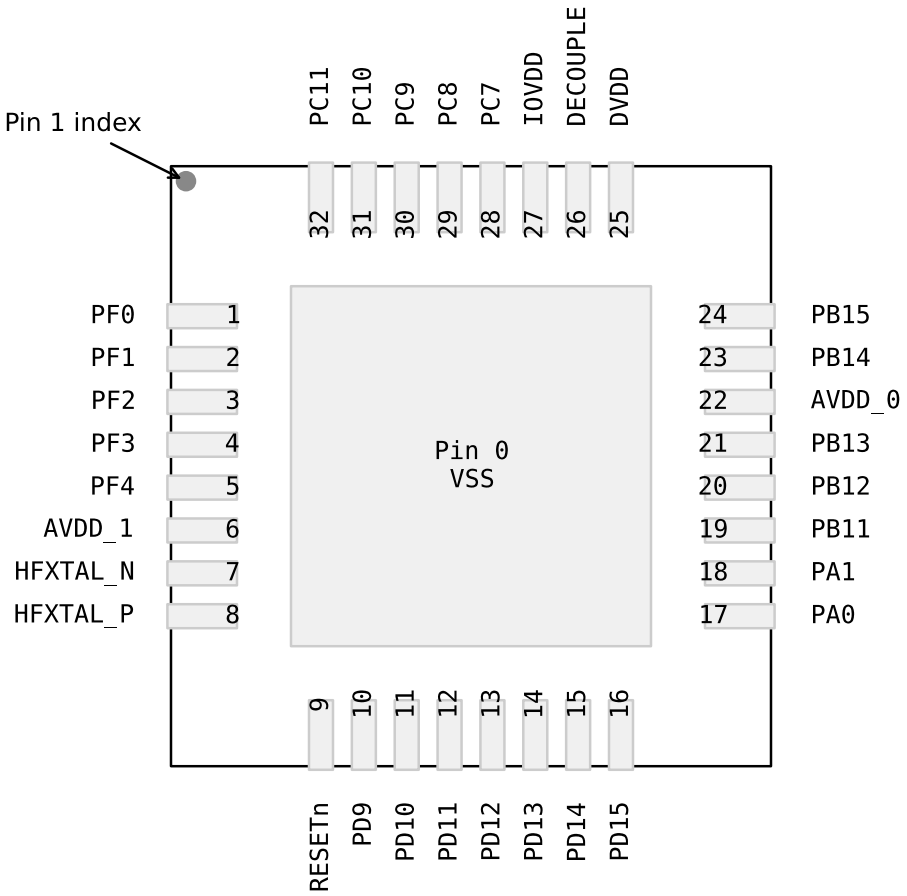


Figure 6.2. EFM32PG1 QFN32 without DC-DC Pinout

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
30	PC9	BUSAY BUSBX	TIM0_CC0 #14 TIM0_CC1 #13 TIM0_CC2 #12 TIM0_CDTI0 #11 TIM0_CDTI1 #10 TIM0_CDTI2 #9 TIM1_CC0 #14 TIM1_CC1 #13 TIM1_CC2 #12 TIM1_CC3 #11 LE- TIM0_OUT0 #14 LE- TIM0_OUT1 #13 PCNT0_S0IN #14 PCNT0_S1IN #13	US0_TX #14 US0_RX #13 US0_CLK #12 US0_CS #11 US0_CTS #10 US0_RTS #9 US1_TX #14 US1_RX #13 US1_CLK #12 US1_CS #11 US1_CTS #10 US1_RTS #9 LEU0_TX #14 LEU0_RX #13 I2C0_SDA #14 I2C0_SCL #13	PRS_CH0 #11 PRS_CH9 #14 PRS_CH10 #3 PRS_CH11 #2 ACMP0_O #14 ACMP1_O #14
31	PC10	BUSAX BUSBY	TIM0_CC0 #15 TIM0_CC1 #14 TIM0_CC2 #13 TIM0_CDTI0 #12 TIM0_CDTI1 #11 TIM0_CDTI2 #10 TIM1_CC0 #15 TIM1_CC1 #14 TIM1_CC2 #13 TIM1_CC3 #12 LE- TIM0_OUT0 #15 LE- TIM0_OUT1 #14 PCNT0_S0IN #15 PCNT0_S1IN #14	US0_TX #15 US0_RX #14 US0_CLK #13 US0_CS #12 US0_CTS #11 US0_RTS #10 US1_TX #15 US1_RX #14 US1_CLK #13 US1_CS #12 US1_CTS #11 US1_RTS #10 LEU0_TX #15 LEU0_RX #14 I2C0_SDA #15 I2C0_SCL #14	CMU_CLK1 #3 PRS_CH0 #12 PRS_CH9 #15 PRS_CH10 #4 PRS_CH11 #3 ACMP0_O #15 ACMP1_O #15 GPIO_EM4WU12
32	PC11	BUSAY BUSBX	TIM0_CC0 #16 TIM0_CC1 #15 TIM0_CC2 #14 TIM0_CDTI0 #13 TIM0_CDTI1 #12 TIM0_CDTI2 #11 TIM1_CC0 #16 TIM1_CC1 #15 TIM1_CC2 #14 TIM1_CC3 #13 LE- TIM0_OUT0 #16 LE- TIM0_OUT1 #15 PCNT0_S0IN #16 PCNT0_S1IN #15	US0_TX #16 US0_RX #15 US0_CLK #14 US0_CS #13 US0_CTS #12 US0_RTS #11 US1_TX #16 US1_RX #15 US1_CLK #14 US1_CS #13 US1_CTS #12 US1_RTS #11 LEU0_TX #16 LEU0_RX #15 I2C0_SDA #16 I2C0_SCL #15	CMU_CLK0 #3 PRS_CH0 #13 PRS_CH9 #16 PRS_CH10 #5 PRS_CH11 #4 ACMP0_O #16 ACMP1_O #16 DBG_SWO #3

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
25	VREGVSS	Voltage regulator VSS			
26	VREGSW	DCDC regulator switching node			
27	VREGVDD	Voltage regulator VDD input			
28	DVDD	Digital power supply.			
29	DECOUPLE	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.			
30	IOVDD	Digital IO power supply.			
31	PC10	BUSAX BUSBY	TIM0_CC0 #15 TIM0_CC1 #14 TIM0_CC2 #13 TIM0_CDTI0 #12 TIM0_CDTI1 #11 TIM0_CDTI2 #10 TIM1_CC0 #15 TIM1_CC1 #14 TIM1_CC2 #13 TIM1_CC3 #12 LE- TIM0_OUT0 #15 LE- TIM0_OUT1 #14 PCNT0_S0IN #15 PCNT0_S1IN #14	US0_TX #15 US0_RX #14 US0_CLK #13 US0_CS #12 US0_CTS #11 US0_RTS #10 US1_TX #15 US1_RX #14 US1_CLK #13 US1_CS #12 US1_CTS #11 US1_RTS #10 LEU0_TX #15 LEU0_RX #14 I2C0_SDA #15 I2C0_SCL #14	CMU_CLK1 #3 PRS_CH0 #12 PRS_CH9 #15 PRS_CH10 #4 PRS_CH11 #3 ACMP0_O #15 ACMP1_O #15 GPIO_EM4WU12
32	PC11	BUSAY BUSBX	TIM0_CC0 #16 TIM0_CC1 #15 TIM0_CC2 #14 TIM0_CDTI0 #13 TIM0_CDTI1 #12 TIM0_CDTI2 #11 TIM1_CC0 #16 TIM1_CC1 #15 TIM1_CC2 #14 TIM1_CC3 #13 LE- TIM0_OUT0 #16 LE- TIM0_OUT1 #15 PCNT0_S0IN #16 PCNT0_S1IN #15	US0_TX #16 US0_RX #15 US0_CLK #14 US0_CS #13 US0_CTS #12 US0_RTS #11 US1_TX #16 US1_RX #15 US1_CLK #14 US1_CS #13 US1_CTS #12 US1_RTS #11 LEU0_TX #16 LEU0_RX #15 I2C0_SDA #16 I2C0_SCL #15	CMU_CLK0 #3 PRS_CH0 #13 PRS_CH9 #16 PRS_CH10 #5 PRS_CH11 #4 ACMP0_O #16 ACMP1_O #16 DBG_SWO #3

Alternate	LOCATION								
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
GPIO_EM4WU12	0: PC10								Pin can be used to wake the system up from EM4
I2C0_SCL	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	I2C0 Serial Clock Line input / output.
I2C0_SDA	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	I2C0 Serial Data input / output.
LETIM0_OUT0	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	LEUART0 Receive input.
LEU0_TX	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	0: PB14								Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	0: PB15								Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Pulse Counter PCNT0 input number 1.
PRS_CH0	0: PF0 1: PF1 2: PF2 3: PF3	4: PF4 5: PF5 6: PF6 7: PF7	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11					Peripheral Reflex System PRS, channel 0.

Alternate	LOCATION								
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
US0_RX	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	USART0 Asynchronous Transmit. Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11 15: PD9	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	USART1 clock input / output.
US1_CS	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 14: PD9 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	USART1 chip select input / output.
US1_CTS	0: PA4 1: PA5 2: PB11 3: PB12	4: PB13 5: PB14 6: PB15 7: PC6	8: PC7 9: PC8 10: PC9 11: PC10	12: PC11 13: PD9 14: PD10 15: PD11	16: PD12 17: PD13 18: PD14 19: PD15	20: PF0 21: PF1 22: PF2 23: PF3	24: PF4 25: PF5 26: PF6 27: PF7	28: PA0 29: PA1 30: PA2 31: PA3	USART1 Clear To Send hardware flow control input.
US1_RTS	0: PA5 1: PB11 2: PB12 3: PB13	4: PB14 5: PB15 6: PC6 7: PC7	8: PC8 9: PC9 10: PC10 11: PC11	12: PD9 13: PD10 14: PD11 15: PD12	16: PD13 17: PD14 18: PD15 19: PF0	20: PF1 21: PF2 22: PF3 23: PF4	24: PF5 25: PF6 26: PF7 27: PA0	28: PA1 29: PA2 30: PA3 31: PA4	USART1 Request To Send hardware flow control output.
US1_RX	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	16: PD9 17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 17: PD9 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

Table 6.9. ACMP1 Bus and Pin Mapping

Port	Bus	CH31	CH30	CH29	CH28	CH27	CH26	CH25	CH24	CH23	CH22	CH21	CH20	CH19	CH18	CH17	CH16	CH15	CH14	CH13	CH12	CH11	CH10	CH9	CH8	CH7	CH6	CH5	CH4	CH3	CH2	CH1	CH0
APORT1X	BUSAX										PF6		PF4		PF2		PF0						PC10		PC8		PC6						
APORT1Y	BUSAY									PF7		PF5		PF3		PF1						PC11		PC9		PC7							
APORT2X	BUSBX									PF7		PF5		PF3		PF1						PC11		PC9		PC7							
APORT2Y	BUSBY										PF6		PF4		PF2		PF0						PC10		PC8		PC6						
APORT3X	BUSCX		PB14		PB12																PA4		PA2		PA0		PD14		PD12		PD10		
APORT3Y	BUSCY	PB15		PB13		PB11														PA5		PA3		PA1		PD15		PD13		PD11		PD9	
APORT4X	BUSDX	PB15		PB13		PB11														PA5		PA3		PA1		PD15		PD13		PD11		PD9	
APORT4Y	BUSDY		PB14		PB12																PA4		PA2		PA0		PD14		PD12		PD10		

7. QFN48 Package Specifications

7.1 QFN48 Package Dimensions

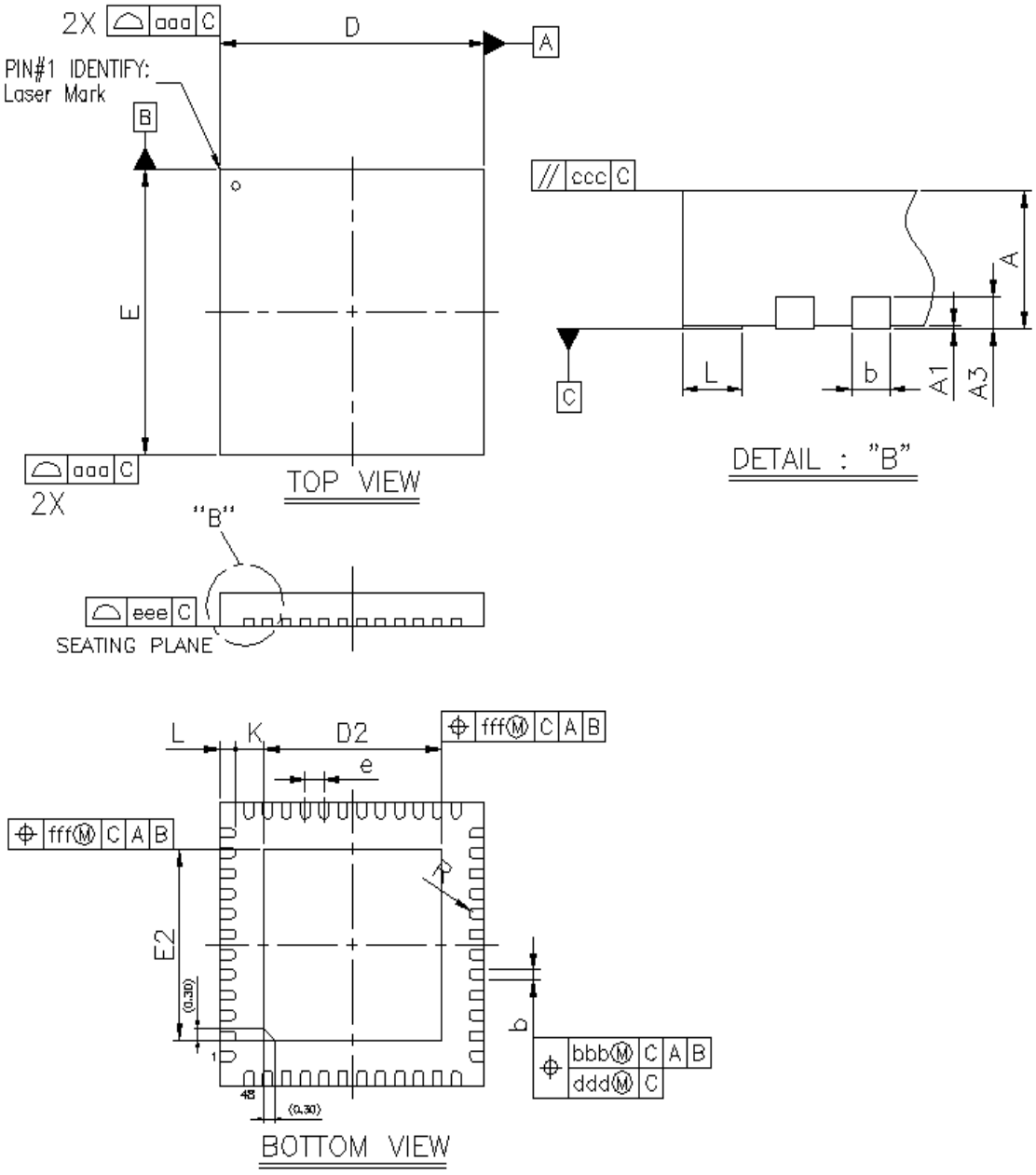


Figure 7.1. QFN48 Package Drawing

8. QFN32 Package Specifications

8.1 QFN32 Package Dimensions

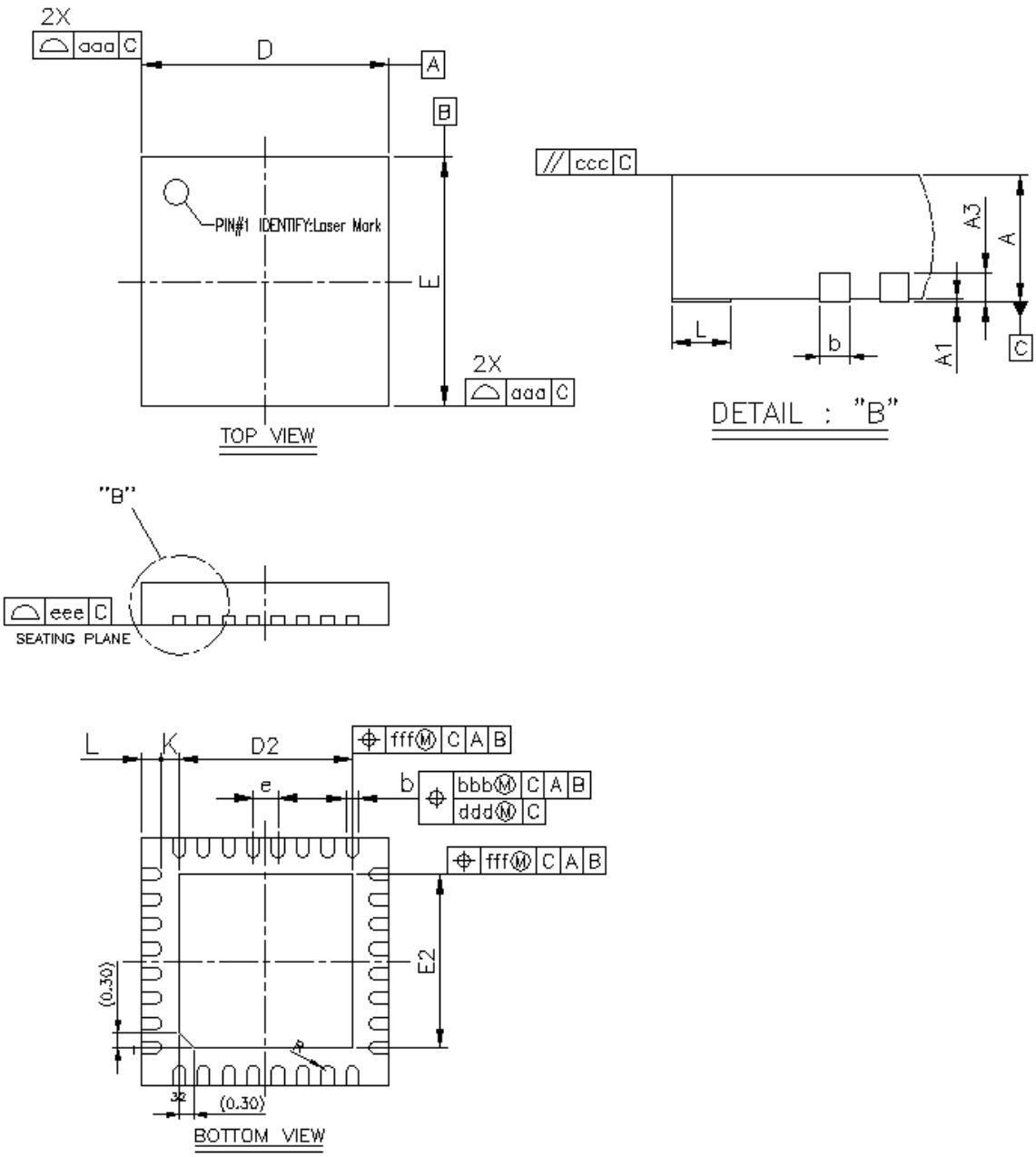
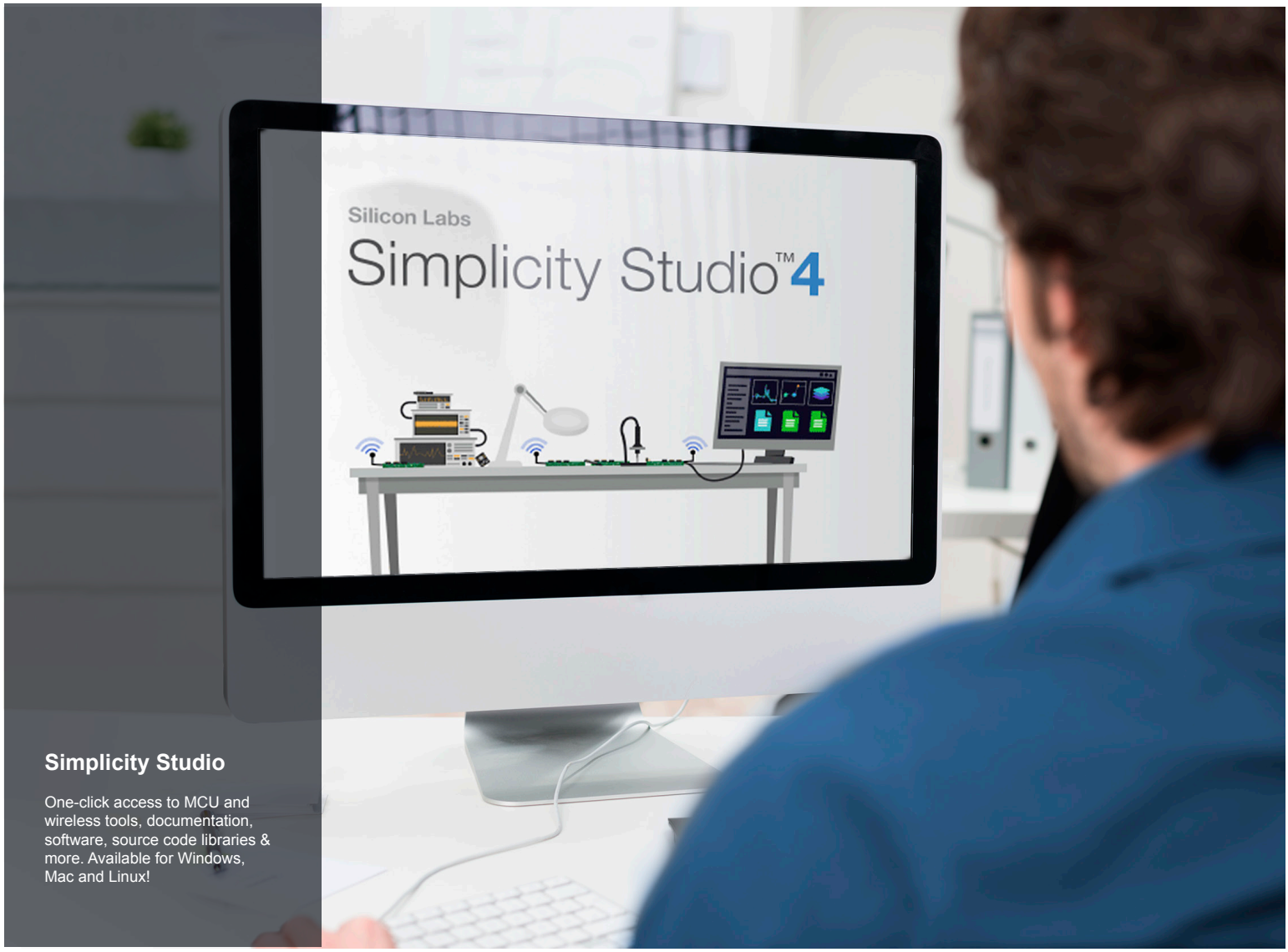


Figure 8.1. QFN32 Package Drawing

9.7 Revision 0.1

Initial release.



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